

WHAT IS CLAIMED IS:

1. A bonding apparatus comprising:

an electronic component supply module that takes out an electronic component from a carrier tape and transfers the taken-out electronic component;

5 a die supply module that has a pickup part for picking up a semiconductor die from a wafer bonded to a dicing sheet by pushing up the semiconductor die, and transfers the picked-up semiconductor die; and

a bonding module for arranging at least one of the semiconductor die supplied by the die supply module and the electronic component supplied by the electronic component supply
10 module on a substrate,

wherein the electronic component supply module has a first transfer part that transfers out the electronic component taken out from the carrier tape from the electronic component supply module,

the die supply module has a second transfer part that transfers out the picked-up
15 semiconductor die from the die supply module, and

one of the first transfer part and the second transfer part is a common transfer path for transferring both the electronic component and the semiconductor die to the bonding module, and the other is an independent transfer path for transferring out one of the electronic component and the semiconductor die to the common transfer path.

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2. The bonding apparatus according to claim 1, wherein the first transfer part and the second transfer part transfer the semiconductor die and the electronic component respectively in a predetermined transfer direction.

25 3. The bonding apparatus according to claim 2, wherein the electronic component supply module, the die supply module, and the bonding module are arranged in this order along

the transfer direction.

4. The bonding apparatus according to any one of claims 1 to 3, wherein the bonding module has an arrangement part capable of receiving the electronic component from the first transfer part and arranging the received electronic component on the substrate, and capable of receiving the semiconductor die from the second transfer part and arranging the received semiconductor die on the substrate.